

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0			2023 20/04	

Note:

1. Material:

1.1 Housing: High temperature thermoplastic with g.f, UL94v-0 LCP

1.2 Contact: copper alloy, $t=0.20\text{mm}$

1.3 Shell: SUS, $t=0.25\text{mm}$

2. Specification:

2.1 Current rating: 1, 5PIN 1.8A Max/2, 3, 4PIN 1A Max.

2.2 Dielectric withstanding

voltage: 100 V(ac) for 1 min.

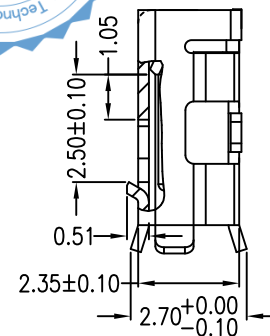
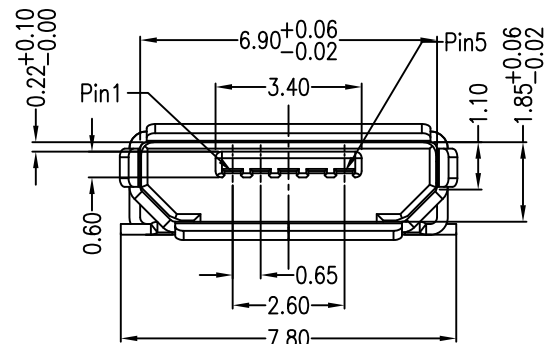
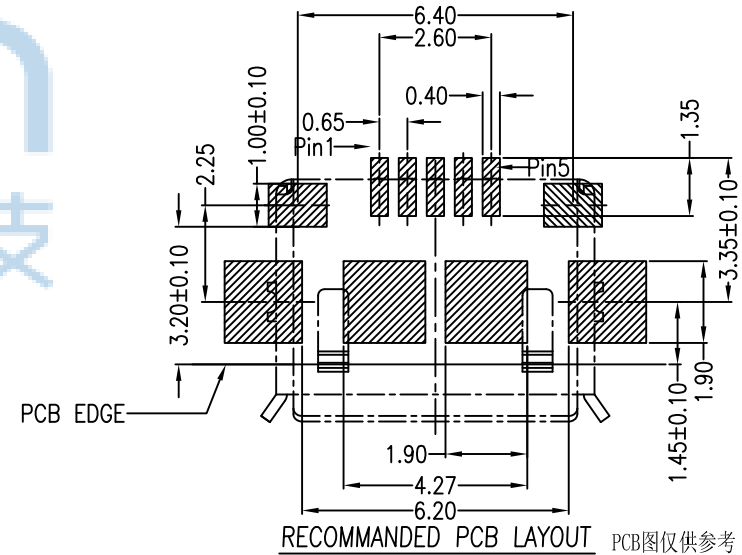
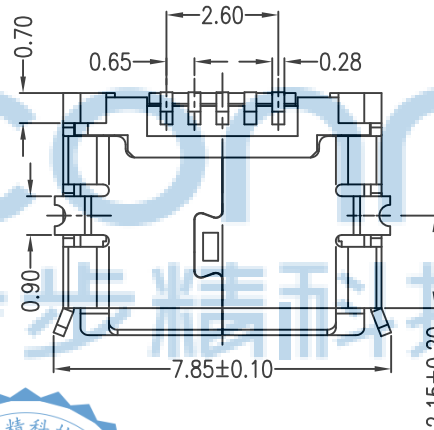
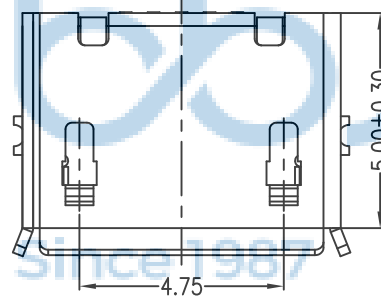
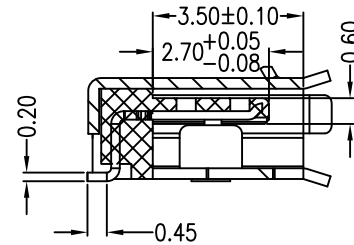
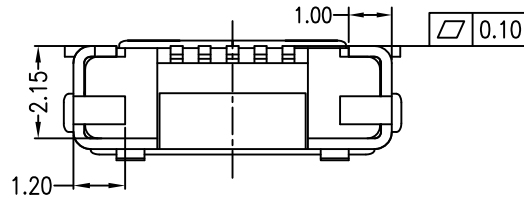
2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

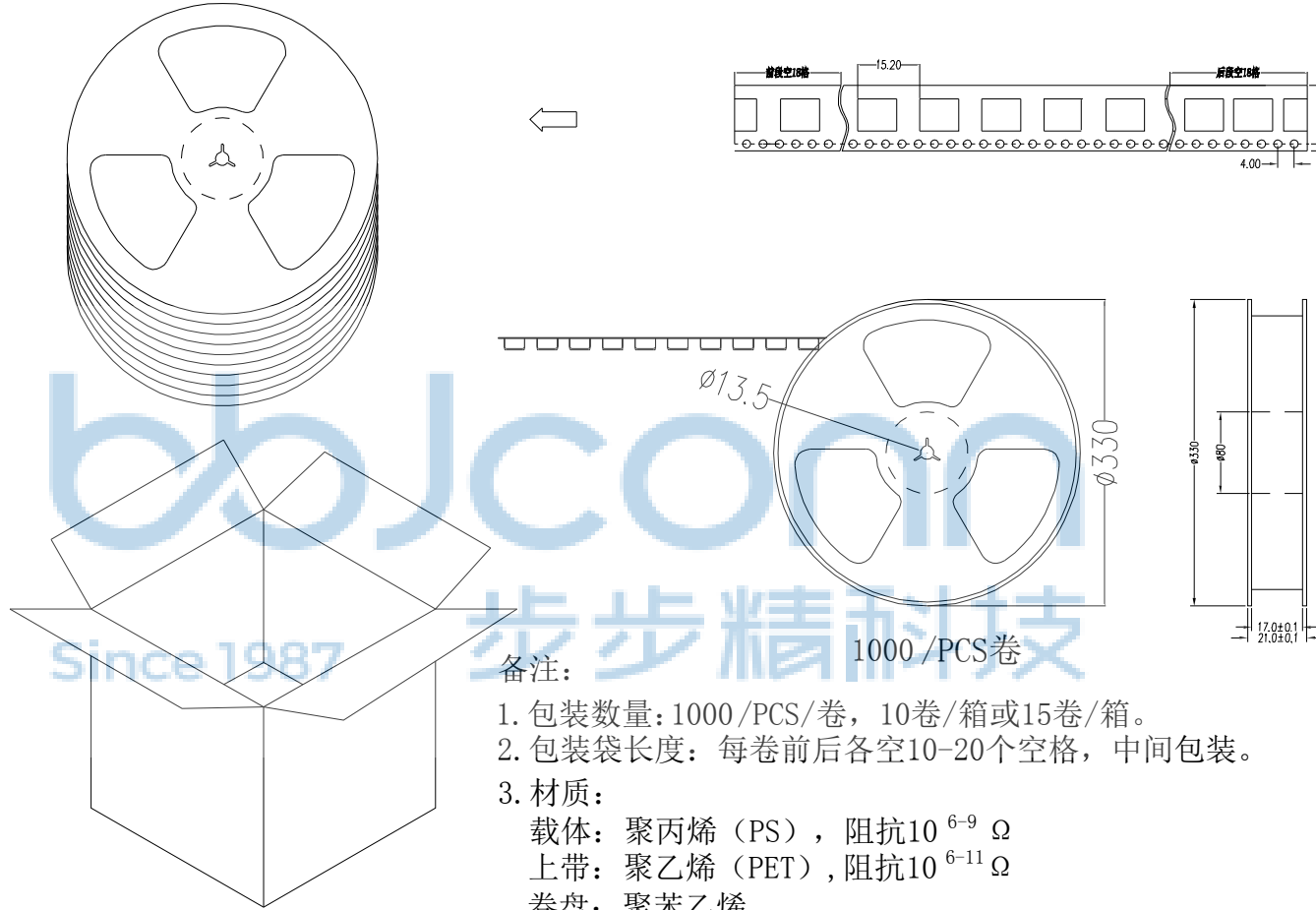
2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min

2.7 Temperature range: -30°C ~ 80°C



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		.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" .X': ±2" .XX': ±1"		NAME: Micro-5P 母座 全贴无柱 L=5.00 卷边 不锈钢外壳	
	APPD.	JM_Zheng	23/05'02		PJ. NO.: MC.01.41-11-1001		
	CHKD.	LYX	23/05'02		SIZE: A4 DRW NO.:		
					FINISH: SEE NOTES		MAT'L.: SEE NOTES
				SCALE: N/A	REV.: A3	UNIT: mm	PAGE: 1/1



备注:

1. 包装数量: 1000 /PCS/ 卷, 10卷/箱或15卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM



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.X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13		X*: $\pm 3^{\circ}$.X*: $\pm 2^{\circ}$ XX*: $\pm 1^{\circ}$		NAME: Micro-5P 母座 全贴无柱 L=5.00 卷边 不锈钢外壳			
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CHKD.	LYX	23/05'02	FINISH: SEE NOTES		MAT'L.: SEE NOTES		
PDWG.NO:	0113-1	DR.	SGF	23/05'02	SCALE: N/A	REV.: A3	UNIT: mm PAGE: 1/1